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LANDSCAPE AND ECOSYSTEM:

MAPPING OF KEY INITIATIVES SUPPORTING RESILIENT EDUCATION SYSTEMS

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MAPPING OF KEY INITIATIVES SUPPORTING RESILIENT EDUCATION SYSTEMS

ABSTRACT

Since the onset of COVID-19, various coalitions, alliances, and collaborations are addressing the global education crisis. However, gaps existing in the education ecosystem are found to be unevenly addressed. The issues related to safety, security, privacy and mental health of education stakeholders, especially, marginalized groups, are found to have lesser focus initiatives. This paper has mapped out key multination initiatives working to bridge critical gaps and those supporting resilient education systems globally.

The multisector stakeholder activities have been categorized as digital infrastructure, digital literacy and skills, digital content and solutions and lastly wellness of educators and learners. Within each of these categories, the name of the organization leading the intervention, its key focus area, the name of its initiative, and general overview of activities have been mapped.

After completion of the mapping, it was observed that the initiatives are lacking in areas such as tracking and reaching out to marginalized and less visible groups who are likely to drop out of the school. The other issues include relevance and accessibility of learning materials and integration of child protection in education service to mitigate and respond to violence. The mapping exercise has also made apparent an increment in startups during COVID-19 working in development of local educational content and solutions for self-learning as well as for educators using different technologies. Many other innovations like educational gaming developed by children for children, making local language digital content accessible for all children, solar powered offline educational technology, and tech solutions supporting out of school children etc. have been observed.

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